| Electronic control apparatus  |   |
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| Abstract  |   |
| An electronic control unit having a housing, a substrate, particularly a hybrid, arranged in the housing and having an electronic control circuit. The electronic control unit also includes at least one device plug secured to the housing having contact elements that are electrically conductively connected to the control circuit of the substrate. A second substrate is arranged in the housing, spatially separated from the first substrate. At least one power component disposed in the housing and, electrically connected to the control circuit on the first substrate. One connecting printed circuit trace disposed in housing and conductively connected to the power component. The connecting printed circuit trace are conductively connected to a contact element, conducting power currents, of the device plug. Using the arrangement, in the event of a large number of contact elements in a device plug, the electrical connecting of the contact elements to the substrate can be simplified. Moreover, the printed circuit trace layout is simplified, an improvement in the EMC protection is achieved, and the dissipation of heat generated by the power component is improved |   |
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